

What is claimed is:

1. A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:
  - an arm having a delivery portion disposed at least partially over the polishing surface;
  - a first nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a first rate; and
  - at least a second nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a second rate that is different than the first rate.
2. The system of claim 1 further comprising a flow control device coupled to the first nozzle.
3. The system of claim 2 further comprising a second control device coupled to the second nozzle.
4. The system of claim 2, wherein the flow control device is a flow control selected from the group consisting of orifices, needle valves, proportional valves, pinch valves, restrictors, mass flow controllers and a metering pumps.
5. The system of claim 1, wherein the arm further comprises a polishing fluid delivery line coupled to both the first and second nozzle.
6. The system of claim 1 further comprising a first fluid source coupled to the first nozzle and a second fluid source coupled to the second nozzle.
7. The system of claim 1 further comprising a plurality of nozzles adapted to flow polishing fluid at a controlled rate.
8. The system of claim 7, wherein each nozzle is independently controllable.

9. The system of claim 1 further comprising a rotating platen adapted to support a polishing material, the polishing material comprising the polishing surface.

10. The apparatus of claim 9, wherein the polishing material is a polyurethane pad or a fixed abrasive pad.

11. The system of claim 10, wherein the polishing material is a web of fixed abrasive.

12. The system of claim 1, wherein the first nozzle is disposed radially inward of the second nozzle relative to the center of rotation of the polishing pad, and wherein the first flow is at least 1.15 time greater than the second flow.

13. The system of claim 1, wherein first flow is at least 1.15 times the second flow rate.

14. The system of claim 1, wherein first flow is about 1.2 to about 20 times the second flow rate.

15. The system of claim 1 further comprising a metrology device adapted to provide information utilized to control at least one of the flows through the nozzles.

16. A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

an arm having a delivery portion disposed at least partially over the polishing surface;

a first means for providing polishing fluid to the polishing surface at a first rate; and

a second means for providing polishing fluid to the polishing surface at a second rate, wherein the second rate is different than the first rate.

17. The system of claim 16, wherein the first and second means are independently controllable.

18. The system of claim 16 further comprising one or more additional means for providing polishing fluid to the polishing surface disposed between the first means and the second means.

19. A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a platen supporting the polishing surface;

a polishing head disposed over the platen;

an arm having a delivery portion disposed at least partially over the polishing surface;

a first nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a first rate; and

at least a second nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a second rate that is different than the first rate.

20. The system of claim 19, wherein at least the first flow is controllable.

21. The system of claim 20, wherein the second flow is controllable.

22. The system of claim 19 further comprising a metrology device adapted to provide information utilized to control at least one of the flows through the nozzles.

23. A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

flowing the polishing fluid onto the pad at a first location at a first rate; and  
flowing the polishing fluid on the pad at a second location at a second rate  
that is different than the first rate.

24. The method of claim 23, wherein the first rate is independently controllable  
relative the second rate.

25. The method of claim 23 further comprising:  
flowing the polishing fluid on the pad at one or more locations between the  
first location and the second location.

26. The method of claim 23, wherein the step of flowing the polishing fluid at a  
first rate further comprises:  
adjusting the flow rate during polishing.

27. The method of claim 26, wherein the step of adjusting further comprises:  
adjusting the flow rate in response to a polishing metric.